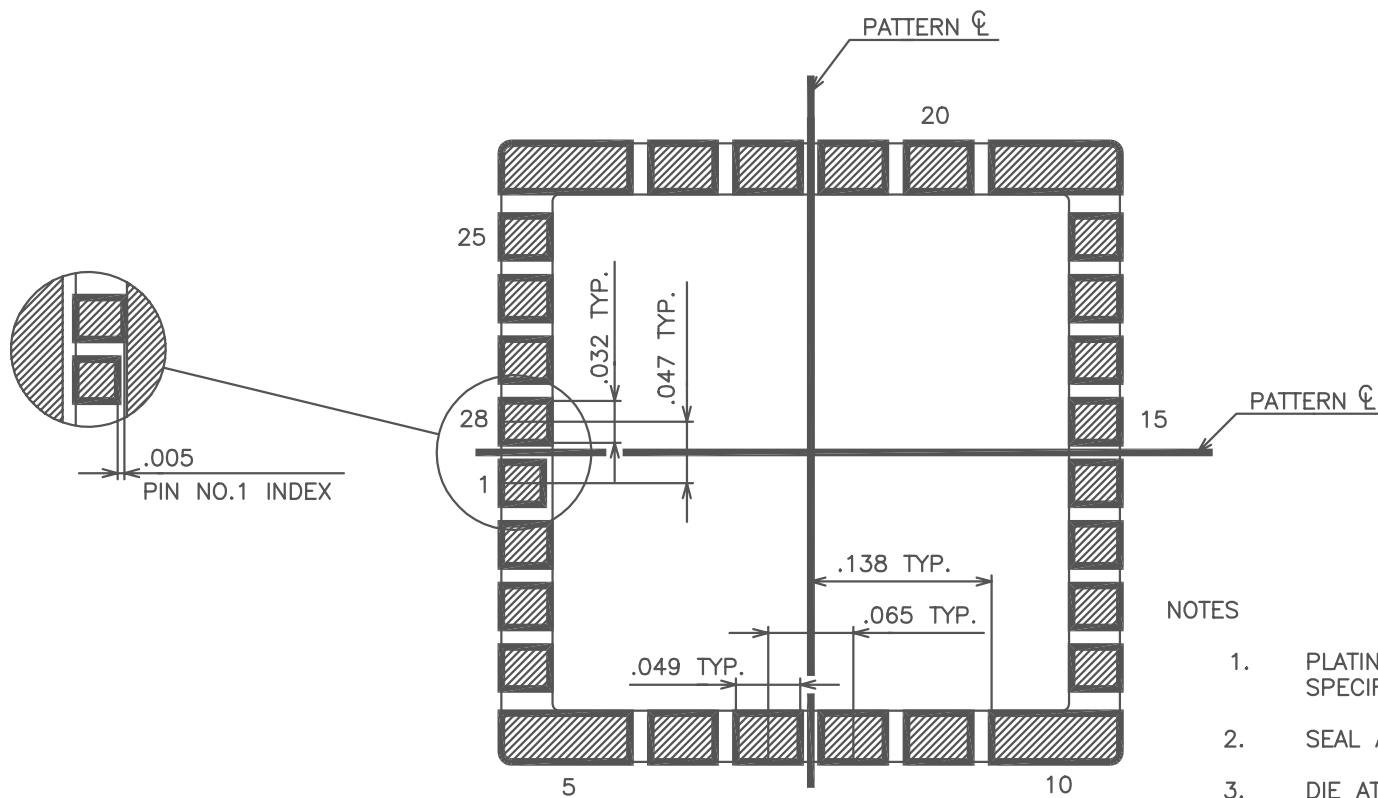


SB028M759-1 S=0
D=0

MODIFICATION					NAME 28 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED ±.005 THIRD ANGLE PROJECTION	DRAWN S.SE	CHECKED S.T T.A	APPROVED K.M	DATE OCT.18.'92
	△	REDRAWN : CONVERTED CAD DATA CHANGED	OCT.18.'92	S.SE	S.T T.A	K.M				
						KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-82759-A		SHEET 1/2	



NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE: 0.35 OHM MAX.

BONDING PATTERN

MODIFICATION						NAME 28 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN S.SE	CHECKED S.T T.A	APPROVED K.M	DATE OCT.18.'92
						SCALE 10 / 1	MATERIAL				
	REDRAWN : CONVERTED CAD DATA	OCT.18.'92	S.SE	S.T T.A	K.M		THIRD ANGLE PROJECTION				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-82759-A		SHEET 2/2	